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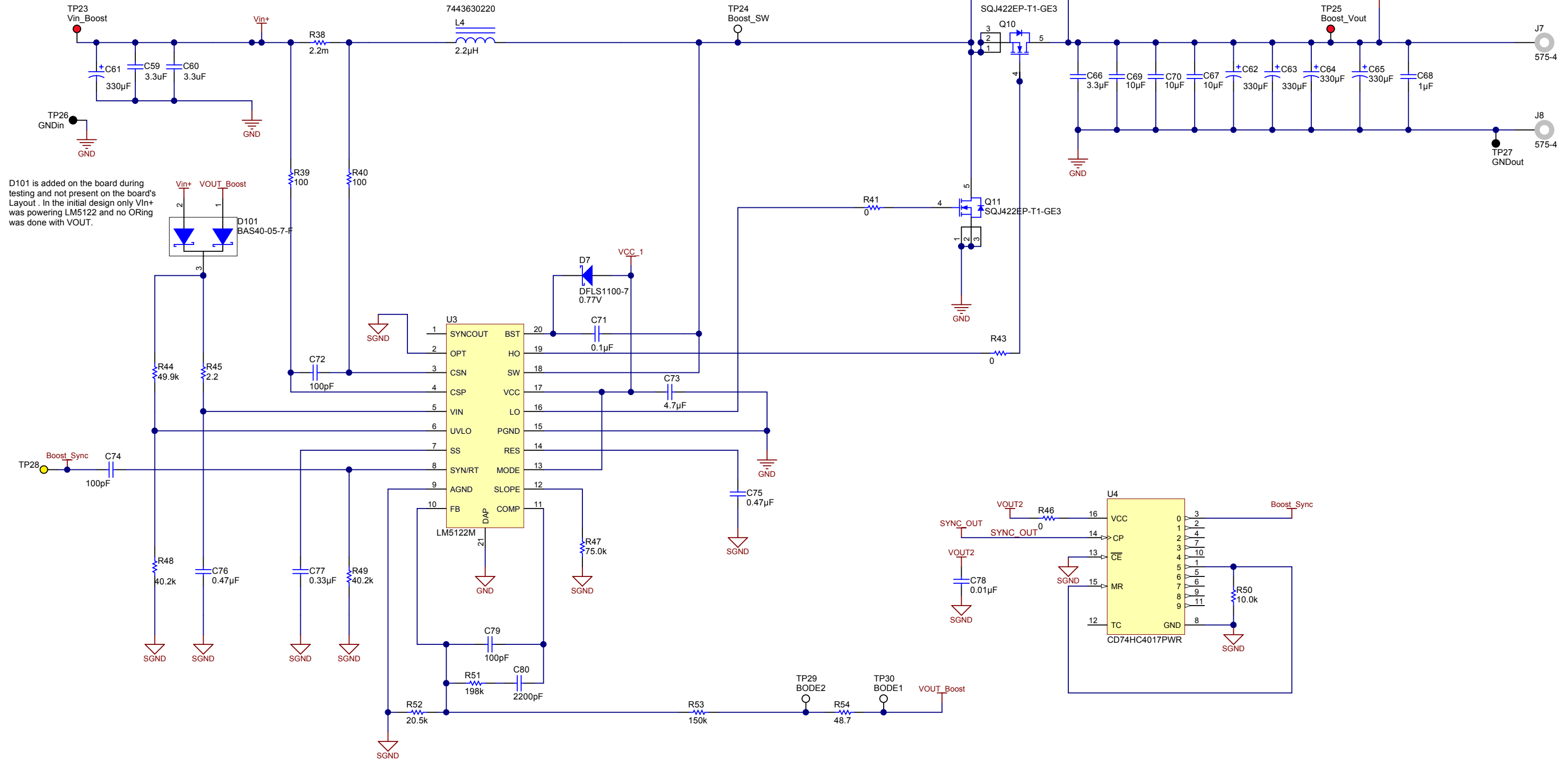
Number: PMP10749 REV2 E1	Mod. Date: 10/30/2015	 TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2015
SVN Rev: Not in version control	Project Title: SMPS design for High Power Automotive Infotainment	
Drawn By:	Sheet Title:	Sheet: 1 of 1
Engineer: Ambresh Tripathi	Assembly Variant: [No Variations]	Size: B
	File: PMP10749_Filters+Reverse REV2.SchDoc	Contact: http://www.ti.com/support

Full Load at 5Vin

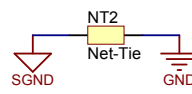
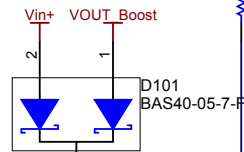
3V-20V Vin

Peak Inductor Current= 22.7A
Isw(In) RMS(Q2+Q3)=14A
Isw(out)RMS(Q1)=14A

10V@10A



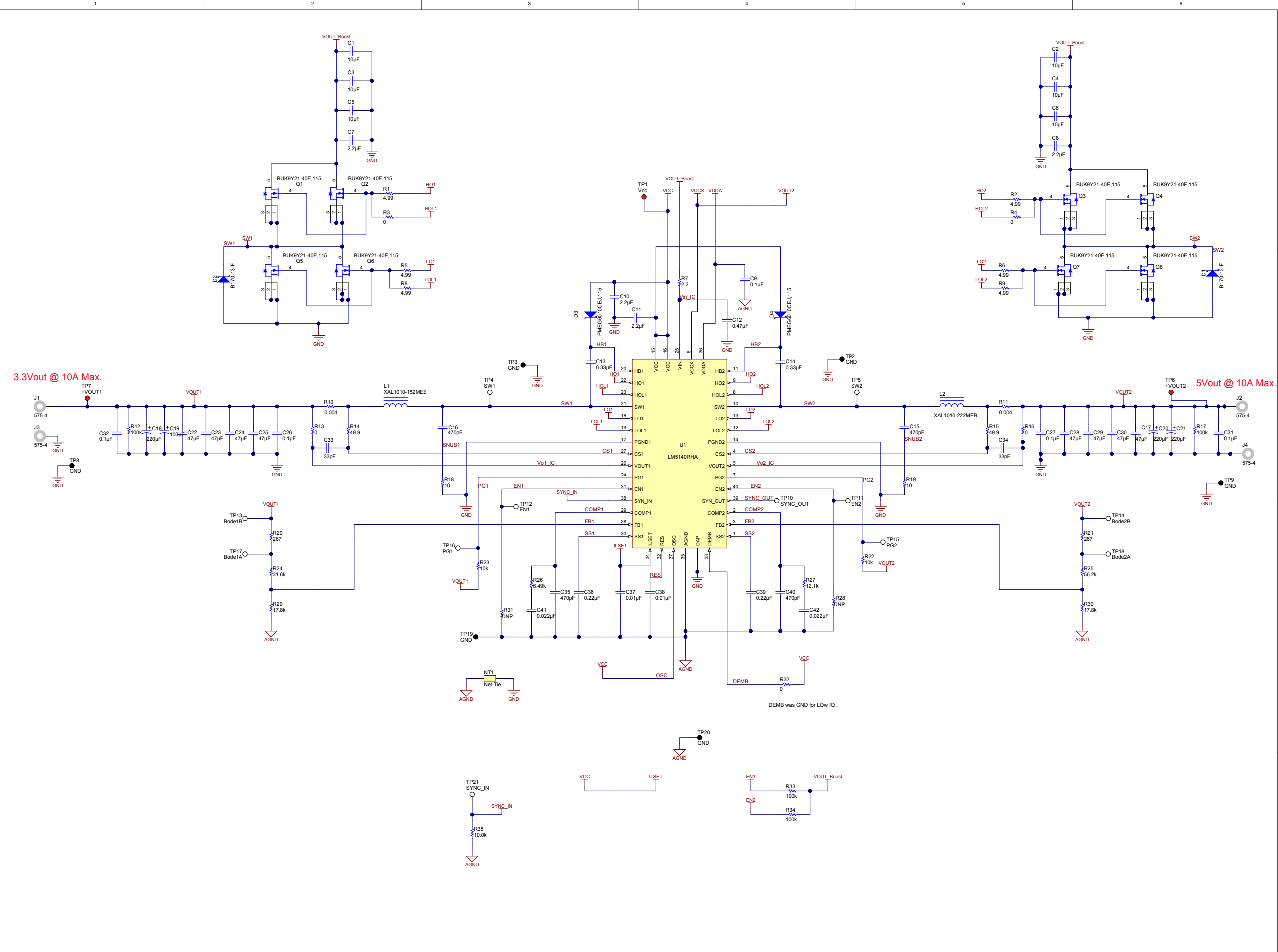
D101 is added on the board during testing and not present on the board's Layout. In the initial design only Vin+ was powering LM5122 and no ORing was done with VOUT.



All of the power ground connections should be connected to a single point. Also, all of the noise sensitive low power ground connections should be connected together near the AGND pin and a single connection should be made to the single point PGND.

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Designed for: Public Release	Mod. Date: 1/13/2016	
Project Title: SMPS design for High Power Automotive Infotainment	Sheet Title:	
Number: PMP10749 REV2 E1	Assembly Variant: [No Variations]	Sheet: 2 of 1
SVN Rev: Not in version control	File: PMP10749_Boost REV2.SchDoc	Size: B
Drawn By:	Engineer: Ambresh Tripathi	Contact: http://www.ti.com/support
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3.3Vout @ 10A Max.

5Vout @ 10A Max.

DEMB was GND for Low IQ.

Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 12/16/2015
TID #: TID	Project Title: SMPS design for High Power Automotive Infotainment	
Number: PMP10749 REV2 E1	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 3 of 1
Drawn By:	File: PMP10749_Buck1_REV2_SchDoc	Size: C
Engineer: Ambresh Tripathi	Contact: http://www.ti.com/support	

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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

FID1 FID2 FID3 FID4 FID5 FID6

PCB Number: PMP10749 REV1_2
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table

Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: PMP10749 REV1_2 E1	Mod. Date: 9/14/2015
SVN Rev: Not in version control	Project Title: SMPS design for High Power Automotive Infotainment
Drawn By:	Sheet Title:
Engineer: Ambresh Tripathi	Assembly Variant: [No Variations]
	File: PMP10749_Hardware.SchDoc
	Size: B
	Contact: http://www.ti.com/support

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